

FIG. 1

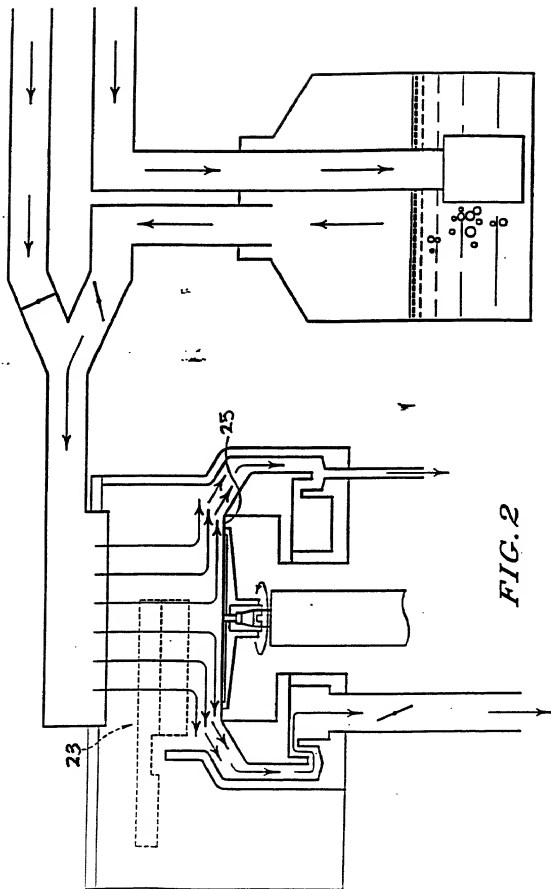


FIG. 2

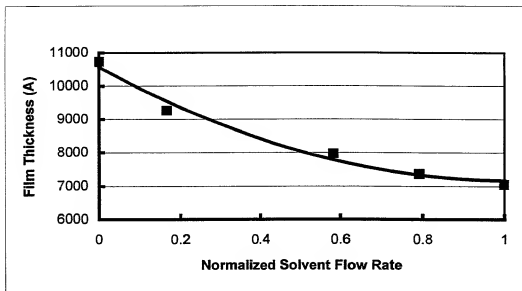


Figure 3a) Mean resist film thickness as a function of solvent concentration at a fixed drying spin speed . Mean film thickness can be varied close to 4000Å by varying the solvent concentration at a fixed 2000 rpm.

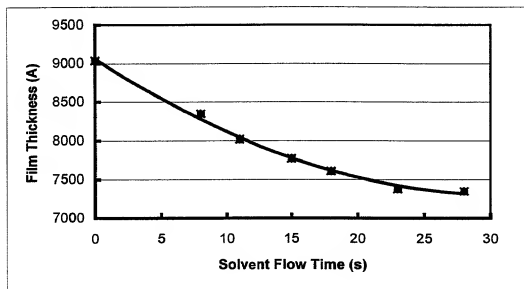
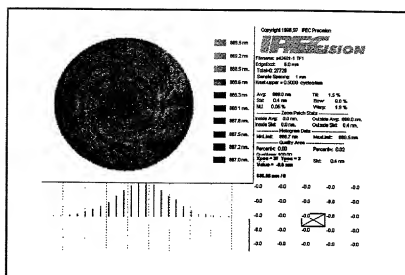


Figure 3b): Film thickness as a function of solvent flow time for a working example.



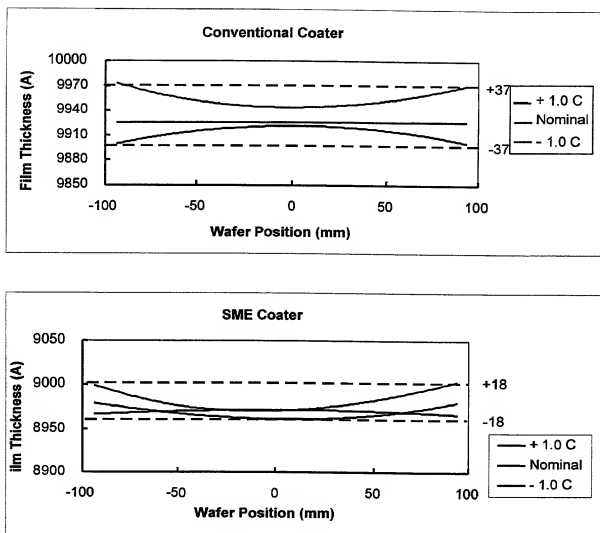


Figure 7: Chill plate temperature latitude comparison of the invention (SME) and conventional coaters for 200mm wafers. The SME coater chill plate temperature latitude of film uniformity is 43% wider than that of a conventional coater.

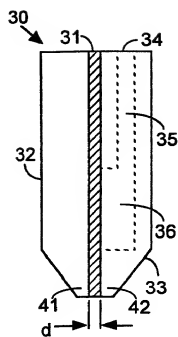


FIG. 8

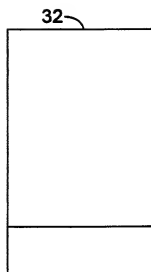


FIG. 9

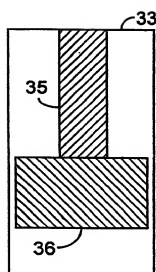


FIG. 10

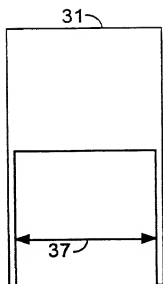


FIG. 11

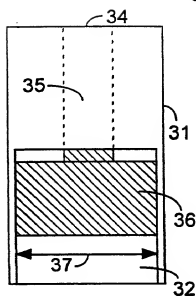


FIG. 12

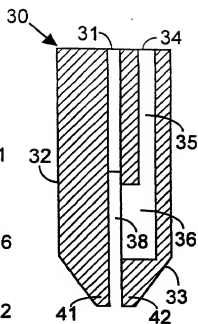


FIG. 13

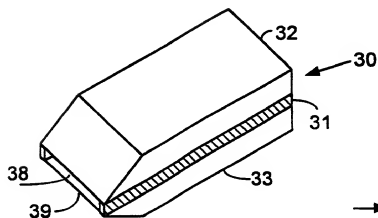


FIG. 14

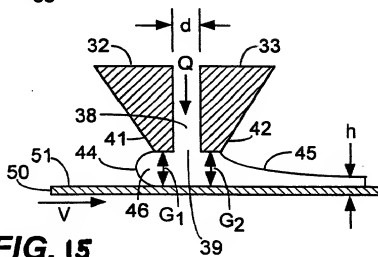
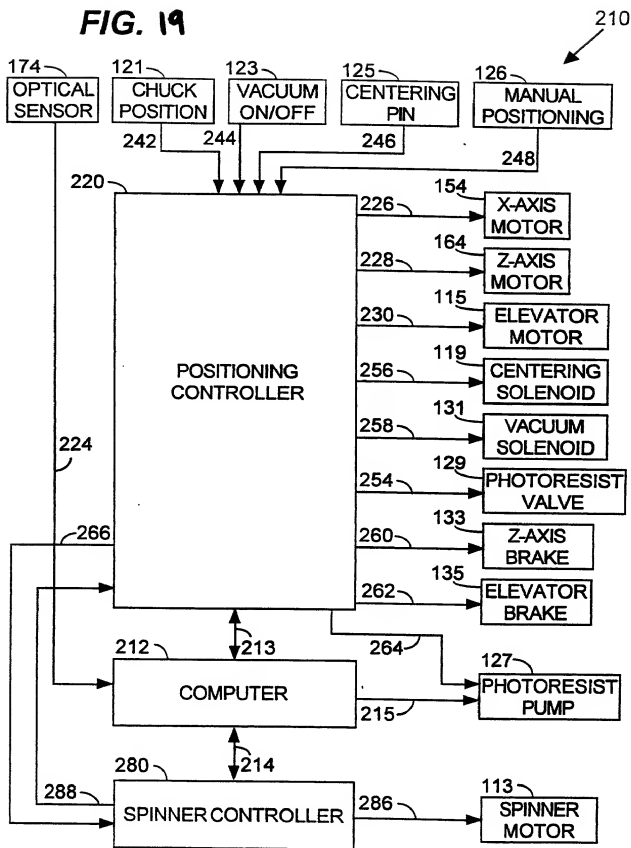


FIG. 15

FIG. 19



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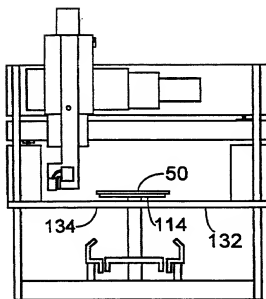


FIG. 20

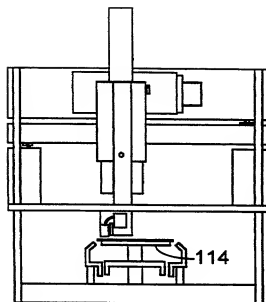


FIG. 21

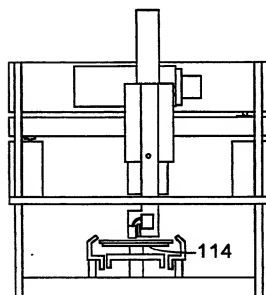


FIG. 22

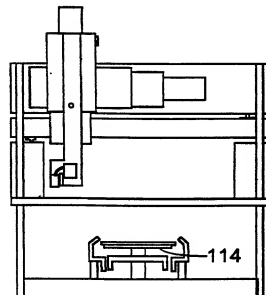


FIG. 23

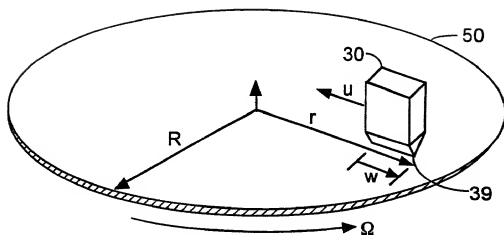


FIG. 24

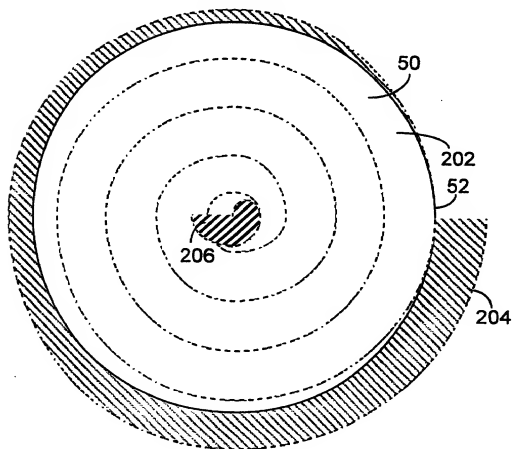


FIG. 25

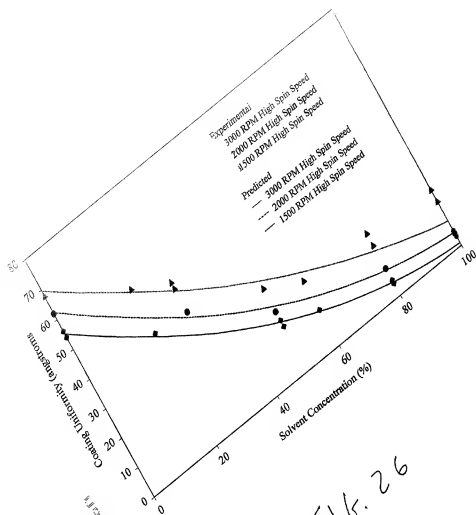


FIG. 26